

## Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

### Listing of Claims:

- 1 1. (Currently amended) A system for permitting orderly shutdown of electronic  
2 components, the system comprising:  
3 an enclosure having an interior surface;  
4 one or more electronic components positioned within the enclosure;  
5 at least one fan positioned within the enclosure for generating an airflow  
6 across the one or more electronic components;  
7 a heat exchanger for cooling the airflow; and  
8 a plurality of phase change material layers disposed upon the interior  
9 surface, at least one of the layers exposed to the airflow within the enclosure  
10 generated by the fan for absorbing heat from the airflow upon a failure  
11 associated with the heat exchanger, a first of the phase change material layers  
12 having a phase change temperature different from a second of the phase change  
13 material layers.
- 1 2. (Currently amended) The system according to claim 1, wherein at least one of  
2 the layers of the phase change material has a phase change temperature that is  
3 above a temperature of the airflow when there is no failure associated with the  
4 heat exchanger, and below a maximum operating temperature of the one or  
5 more electronic components.
- 1 3. (Original) The system according to claim 1, wherein the heat exchanger is a fluid  
2 to air heat exchanger.
- 1 4. (Original) The system according to claim 3, wherein the fluid to air heat  
2 exchanger is coupled to a fluidic circuit.

- 1 5. (Original) The system according to claim 4, wherein the fluidic circuit circulates  
2 one of a refrigerant and water.
- 1 6. (Original) The system according to claim 1, wherein the heat exchanger is a  
2 thermoelectric device.
- 1 7. (Original) The system according to claim 1, wherein the phase change material  
2 is enclosed in a heat conductive container.
- 1 8. (Original) The system according to claim 7, wherein the container includes fins.
- 1 9. (Previously presented) The system according to claim 1, wherein the phase  
2 change material is in micro-encapsulated form that is embedded in a coating  
3 applied to one or more interior surfaces of the enclosure.
- 1 10. (Previously presented) The system according to claim 1, wherein one or more  
2 interior surfaces of the enclosure is coated with the phase change material, the  
3 phase change material encapsulated by a sealing coat.
- 1 11. (Original) The system according to claim 1, further comprising:  
2 a temperature sensor for sensing temperature within the enclosure; and  
3 a high-temperature indication indicative of a high temperature within the  
4 enclosure, the high temperature being lower than a phase change temperature of  
5 the phase change material.
- 1 12. (Original) The system according to claim 1, wherein the phase change material  
2 is a material chosen from the group of materials consisting of a paraffin, a  
3 hydrated salt, a metal, an alloy and an organic acid.
- 1 13. (Original) The system according to claim 1, wherein the at least one fan  
2 substantially recirculates air within the enclosure.

1 14. (Original) The system according to claim 1, wherein the one or more electronic  
2 components includes at least one blade server.

1 15. (Currently amended) A method for cooling one or more electronic components  
2 positioned in an enclosure, the method comprising:  
3 providing an air cooling element within the enclosure;  
4 generating an airflow across the cooling element and one or more  
5 electronic components positioned within the enclosure; and  
6 cooling the airflow using a plurality of layers of phase change material  
7 upon a failure in the cooling element, the phase change material positioned  
8 within on an interior surface of the enclosure and exposed to the airflow within  
9 the enclosure generated by the fan.

1 16. (Original) The method according to claim 15, wherein providing the air cooling  
2 element includes:  
3 moving fluid through a fluidic circuit, the fluidic circuit including a fluid to air  
4 heat exchanger.

1 17. (Original) The method according to claim 16, further comprising pumping one of  
2 a water and a refrigerant through the fluidic circuit.

1 18. (Original) The method according to claim 15, wherein the air cooling element is a  
2 thermoelectric device.

1 19. (Original) The method according to claim 15, further comprising providing an  
2 indication indicative of a high temperature condition within the enclosure.

1 20. (Original) The method according to claim 15, further including shutting down the  
2 one or more electronic components upon a failure in the fluidic circuit.

- 1 21. (Original) The method according to claim 15, wherein the phase change material  
2 has a melting point that is above a temperature of the airflow when there is no  
3 failure in the air cooling element, and below a maximum operating temperature of  
4 the one or more components.
- 1 22. (Original) The method according to claim 15, further comprising enclosing the  
2 phase change material in a container.
- 1 23. (Original) The method according to claim 15, further comprising encapsulating  
2 the phase change material in a surface positioned within the airflow.
- 1 24. (Original) The method according to claim 15, further comprising:  
2 applying the phase change material to a surface positioned within the  
3 airflow; and  
4 applying a sealing coat on top of the phase change material.
- 1 25. (Original) The method according to claim 15, wherein the one or more electronic  
2 components includes at least one blade server.
- 1 26. (Currently amended) A cooling system comprising:  
2 an enclosure;  
3 one or more electronic components positioned within the enclosure;  
4 means for generating an airflow across the one or more electronic  
5 components;  
6 cooling means for cooling the airflow; and  
7 a phase change material at least partially comprising a hydrated salt and  
8 positioned within the enclosure in the airflow generated by the fan, the phase  
9 change material for absorbing heat from the airflow upon a failure in the cooling  
10 means.

- 1 27. (Original) The cooling system according to claim 26, wherein the means for  
2 generating the airflow includes a fan.  
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- 1 28. (Original) The cooling system according to claim 26, wherein the cooling means  
2 includes a fluid to air heat exchanger.
- 1 29. (Original) The cooling system according to claim 28, wherein the fluid to air heat  
2 exchanger is coupled to a fluidic circuit that circulates one of a refrigerant and  
3 water.
- 1 30. (Original) The cooling system according to claim 26, wherein the cooling means  
2 includes a thermoelectric device.
- 1 31. (Original) The cooling system according to claim 26, wherein the phase change  
2 material is enclosed in a container.
- 1 32. (Original) The cooling system according to claim 31, wherein the container  
2 includes fins for dissipating heat.
- 1 33. (Original) The cooling system according to claim 26, wherein the phase change  
2 material is encapsulated in a surface positioned within the airflow.
- 1 34. (Previously presented) The cooling system according to claim 26, wherein one  
2 or more interior surfaces of the enclosure is coated with the phase change  
3 material, the phase change material encapsulated by a sealing coat.
- 1 35. (Original) The cooling system according to claim 26, wherein the phase change  
2 material is a material chosen from the group of materials consisting of a paraffin,  
3 a hydrated salt, a metal, an alloy and an organic acid.

1 36. (Original) The method according to claim 26, wherein the one or more electronic  
2 components includes at least one blade server.